



**THE DATASHEET OF
SN74CBT3253DBRG4**

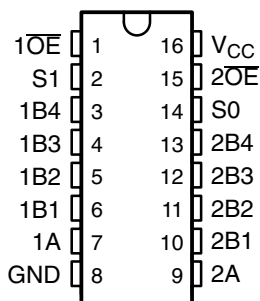


SN74CBT3253 DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

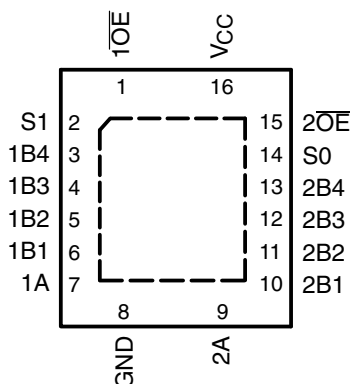
SCDS0180 – MAY 1995 – REVISED JANUARY 2004

● **TTL-Compatible Input Levels**

**D, DB, DBQ, OR PW PACKAGE
(TOP VIEW)**



**RGY PACKAGE
(TOP VIEW)**



description/ordering information

The SN74CBT3253 is a dual 1-of-4 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

1OE, 2OE, S0, and S1 select the appropriate B output for the A-input data.

ORDERING INFORMATION

| T _A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|-------------------|----------------|-----------------------|------------------|
| -40°C to 85°C | QFN – RGY | Tape and reel | SN74CBT3253RGYR | CU253 |
| | SOIC – D | Tube | SN74CBT3253D | CBT3253 |
| | | Tape and reel | SN74CBT3253DR | |
| | SSOP – DB | Tape and reel | SN74CBT3253DBR | CU253 |
| | SSOP (QSOP) – DBQ | Tape and reel | SN74CBT3253DBQR | CU253 |
| | TSSOP – PW | Tube | SN74CBT3253PW | CU253 |
| Tape and reel | | SN74CBT3253PWR | | |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

| INPUTS | | | | FUNCTION |
|--------|-----|----|----|-------------------------|
| 1OE | 2OE | S1 | S0 | |
| X | H | X | X | Disconnect 1A and 2A |
| H | X | X | X | Disconnect 1A and 2A |
| L | L | L | L | 1A to 1B1 and 2A to 2B1 |
| L | L | L | H | 1A to 1B2 and 2A to 2B2 |
| L | L | H | L | 1A to 1B3 and 2A to 2B3 |
| L | L | H | H | 1A to 1B4 and 2A to 2B4 |



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



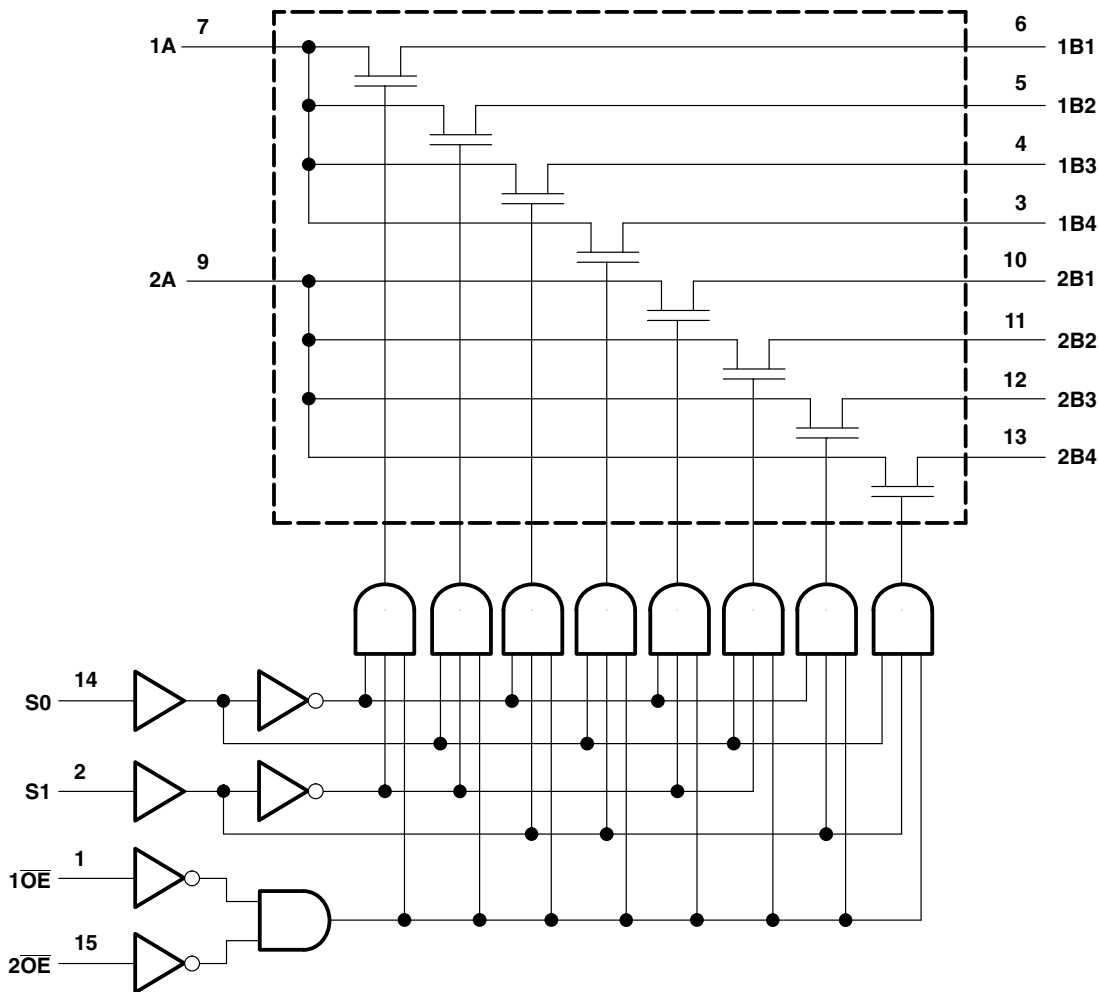
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SN74CBT3253 DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS0180 – MAY 1995 – REVISED JANUARY 2004

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|--|----------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to 7 V |
| Continuous channel current | 128 mA |
| Input clamp current, I_K ($V_{I/O} < 0$) | -50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): D package | 73°C/W |
| (see Note 2): DB package | 82°C/W |
| (see Note 2): DBQ package | 90°C/W |
| (see Note 2): PW package | 108°C/W |
| (see Note 3): RGY package | 39°C/W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-5.



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SN74CBT3253

DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS0180 – MAY 1995 – REVISED JANUARY 2004

recommended operating conditions (see Note 4)

| | MIN | MAX | UNIT |
|--|-----|-----|------|
| V _{CC} Supply voltage | 4 | 5.5 | V |
| V _{IH} High-level control input voltage | 2 | | V |
| V _{IL} Low-level control input voltage | | 0.8 | V |
| T _A Operating free-air temperature | -40 | 85 | °C |

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP† | MAX | UNIT | |
|----------------------|----------------|----------------------------|---|------------------------|------|------|------|---|
| V _{IK} | | V _{CC} = 4.5 V, | I _I = -18 mA | | | -1.2 | V | |
| I _I | | V _{CC} = 5 V, | V _I = 5.5 V or GND | | | ±1 | μA | |
| I _{CC} | | V _{CC} = 5.5 V, | I _O = 0, V _I = V _{CC} or GND | | | 3 | μA | |
| ΔI _{CC} ‡ | Control inputs | V _{CC} = 5.5 V, | One input at 3.4 V, Other inputs at V _{CC} or GND | | | 2.5 | mA | |
| C _i | Control inputs | V _I = 3 V or 0 | | | | 3.5 | pF | |
| C _{io(OFF)} | A port | V _O = 3 V or 0, | OE = V _{CC} | | | 10 | pF | |
| | B port | | | | | 4 | | |
| r _{on} § | | V _{CC} = 4.5 V | V _I = 0 | I _I = 64 mA | | 5 | 7 | Ω |
| | | | | I _I = 30 mA | | 5 | 7 | |
| | | | V _I = 2.4 V, | I _I = 15 mA | | 10 | 15 | |

† All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 4 V | | V _{CC} = 5 V ± 0.5 V | | UNIT |
|------------------------------|--------------|-------------|-----------------------|-----|-------------------------------|-----|------|
| | | | MIN | MAX | MIN | MAX | |
| t _{pd} [¶] | A or B | B or A | 0.35 | | 0.25 | | ns |
| t _{pd} | S | A or B | 6.6 | | 1.6 | 6.2 | ns |
| t _{en} | S | A or B | 7.1 | | 1.3 | 6.3 | ns |
| | OE | | 7.3 | | 1.4 | 6.4 | |
| t _{dis} | S | A or B | 7.9 | | 1.1 | 7.4 | ns |
| | OE | | 7.3 | | 2.3 | 7 | |

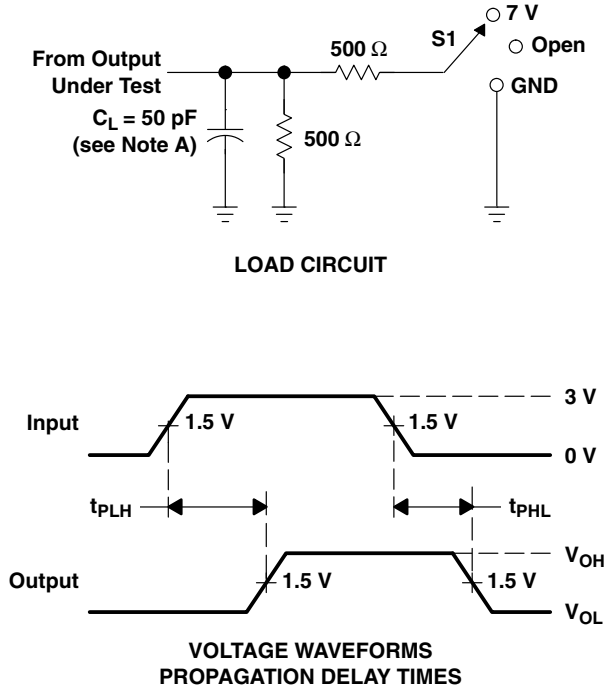
¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



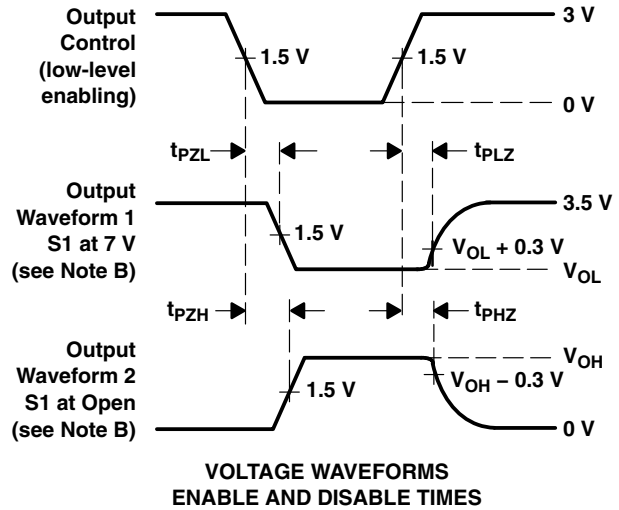
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SCDS0180 – MAY 1995 – REVISED JANUARY 2004

PARAMETER MEASUREMENT INFORMATION



| TEST | S1 |
|------------------------------------|------|
| t _{pd} | Open |
| t _{PLZ} /t _{PZL} | 7 V |
| t _{PHZ} /t _{PZH} | Open |



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PHL} and t_{PLH} are the same as t_{pd}.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74CBT3253D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CBT3253 | Samples |
| SN74CBT3253DBQR | ACTIVE | SSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | CU253 | Samples |
| SN74CBT3253DBR | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CU253 | Samples |
| SN74CBT3253DBRG4 | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CU253 | Samples |
| SN74CBT3253DR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CBT3253 | Samples |
| SN74CBT3253DRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CBT3253 | Samples |
| SN74CBT3253PW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CU253 | Samples |
| SN74CBT3253PWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | CU253 | Samples |
| SN74CBT3253RGYR | ACTIVE | VQFN | RGY | 16 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | CU253 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74CBT3253DBQR | SSOP | DBQ | 16 | 2500 | 330.0 | 12.5 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| SN74CBT3253DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74CBT3253PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74CBT3253RGYR | VQFN | RGY | 16 | 3000 | 330.0 | 12.4 | 3.8 | 4.3 | 1.5 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74CBT3253DBQR | SSOP | DBQ | 16 | 2500 | 340.5 | 338.1 | 20.6 |
| SN74CBT3253DR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74CBT3253PWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74CBT3253RGYR | VQFN | RGY | 16 | 3000 | 367.0 | 367.0 | 35.0 |

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



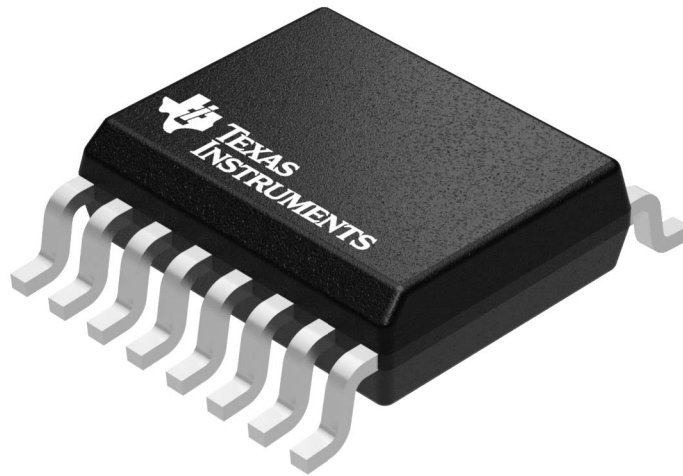
- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

GENERIC PACKAGE VIEW

DBQ 16

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

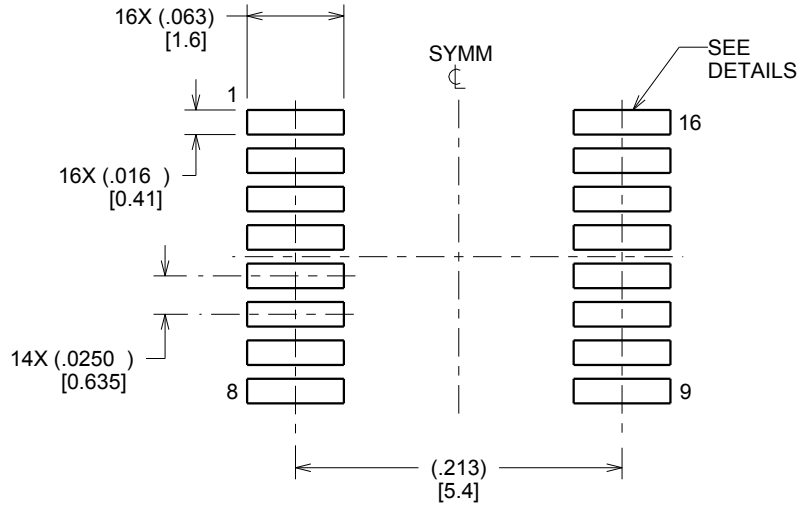
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EXAMPLE BOARD LAYOUT

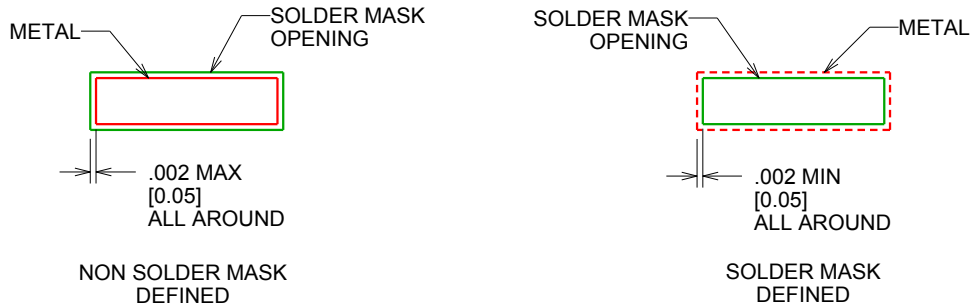
DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4214846/A 03/2014

NOTES: (continued)

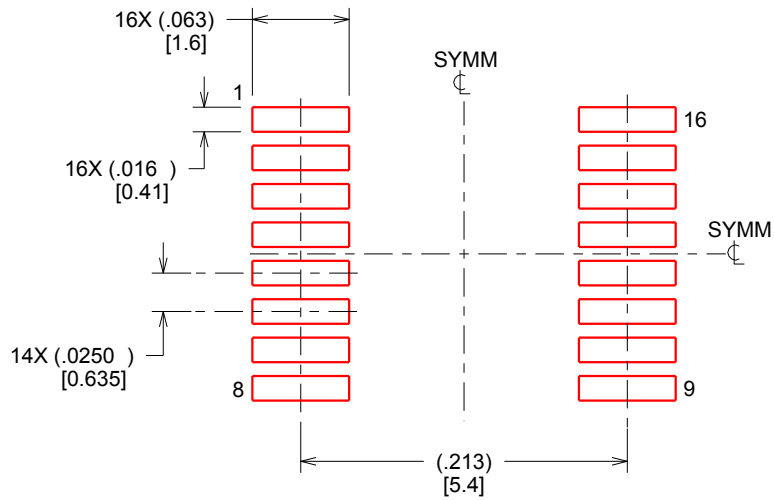
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.127 MM] THICK STENCIL
SCALE:8X

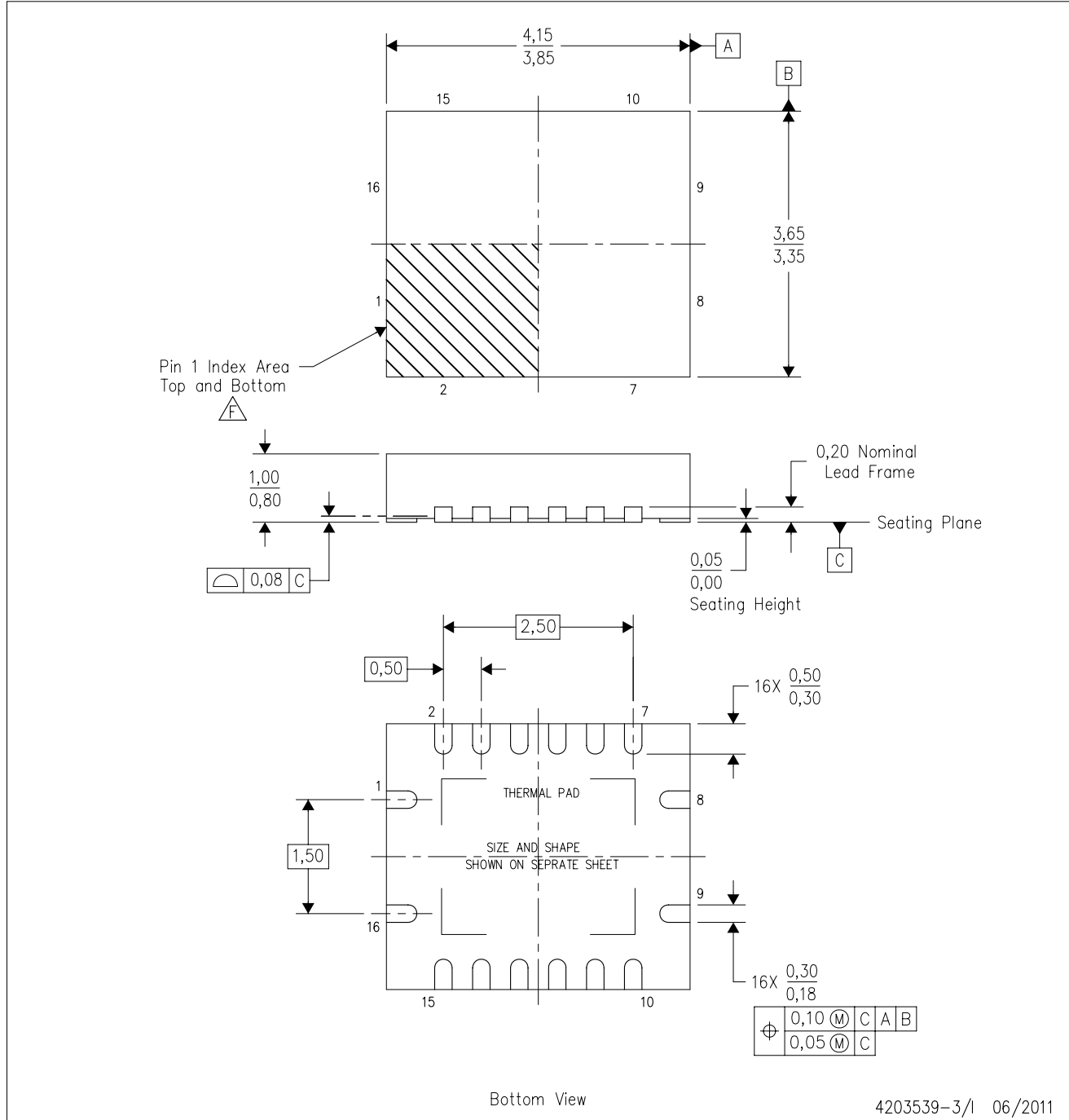
4214846/A 03/2014

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-3/1 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N16)

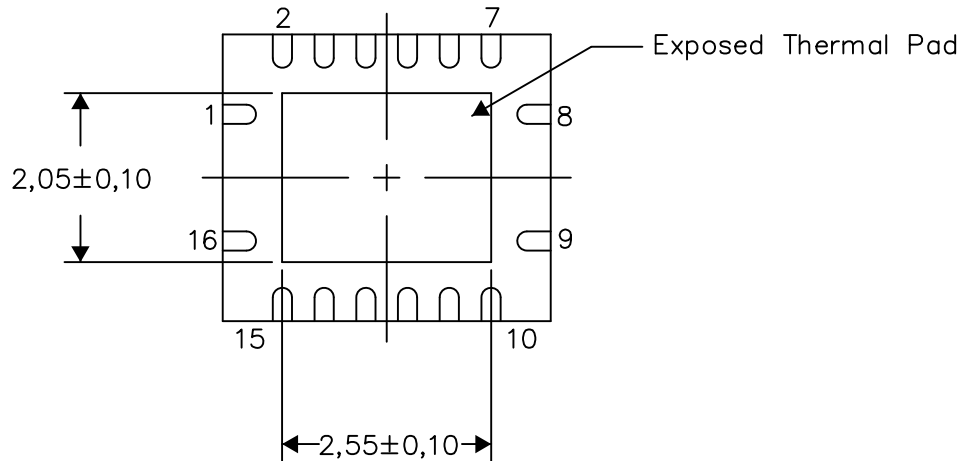
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

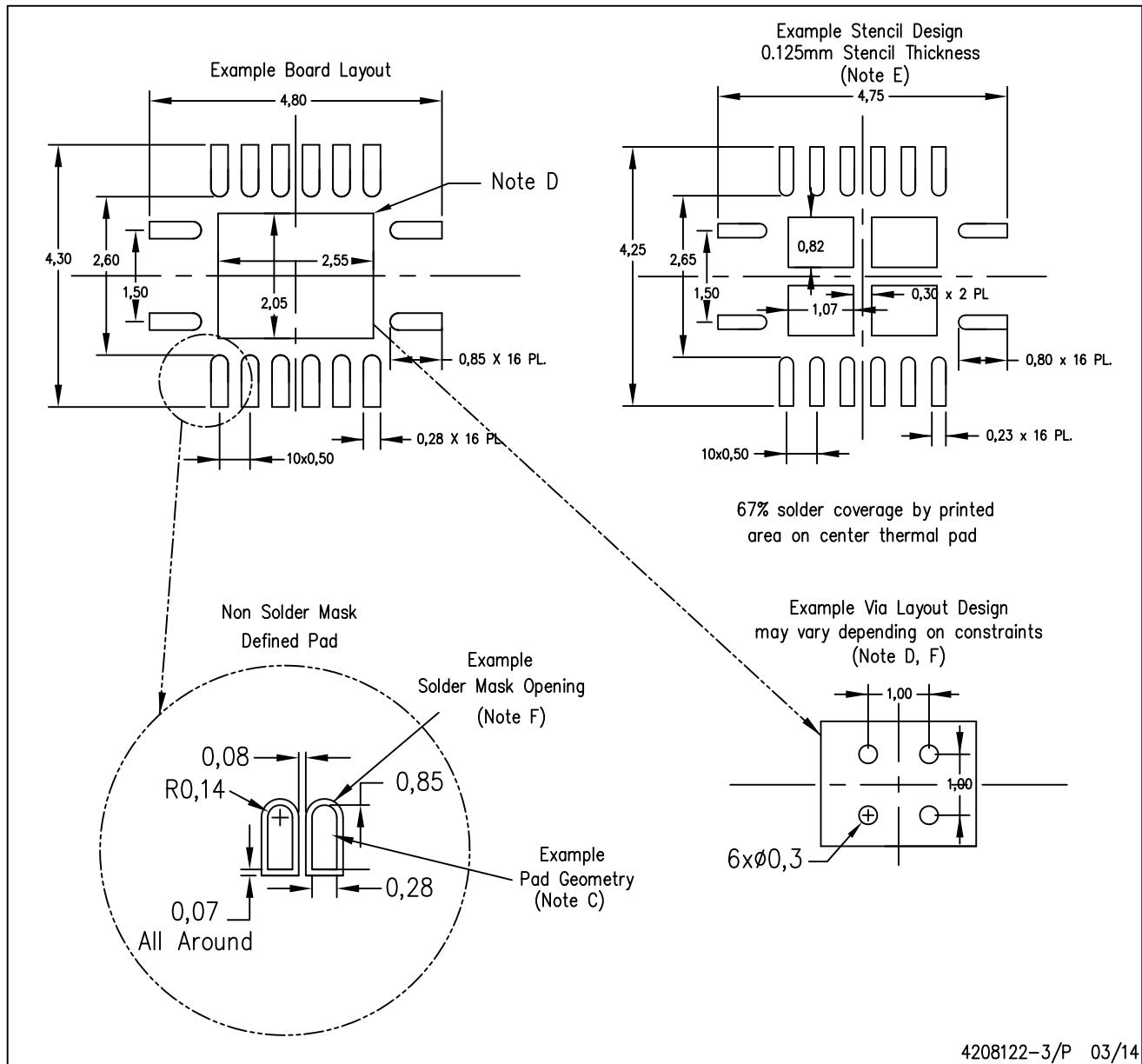
Exposed Thermal Pad Dimensions

4206353-3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-3/P 03/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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